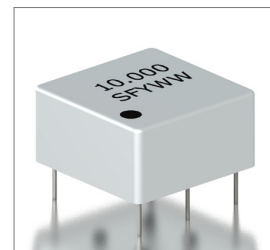
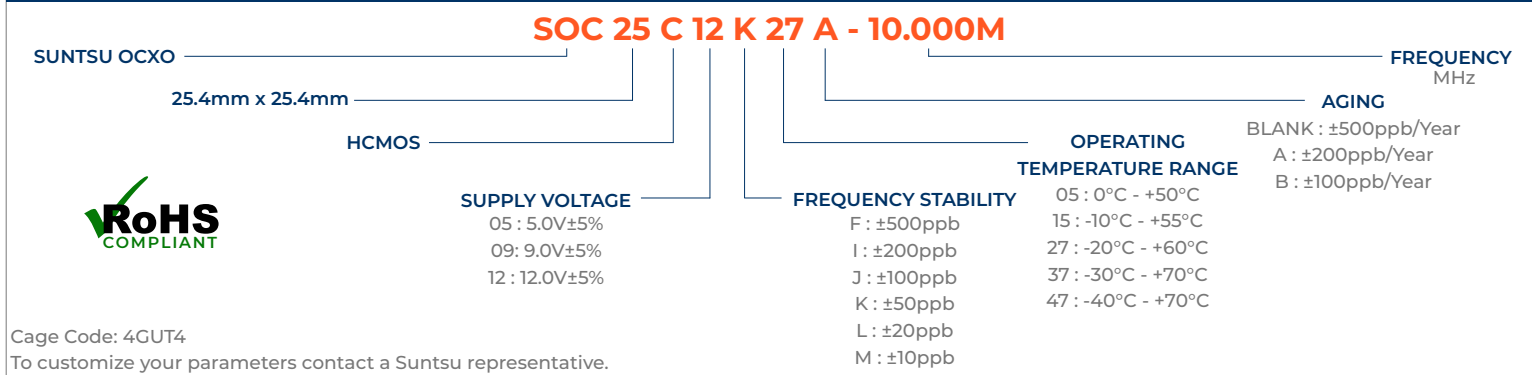


Features
<ul style="list-style-type: none"> ±10ppb (Frequency Stability) Available HCMOS/TTL OCXO

Applications
<ul style="list-style-type: none"> Military Communication Equipment Base Stations Test Equipment Synthesizers Digital Switching



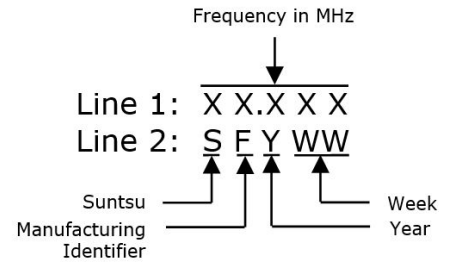
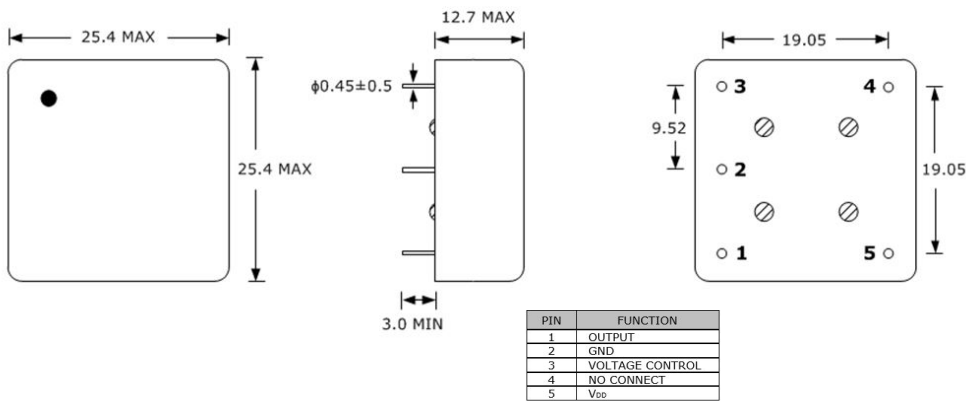
Part Numbering Guide



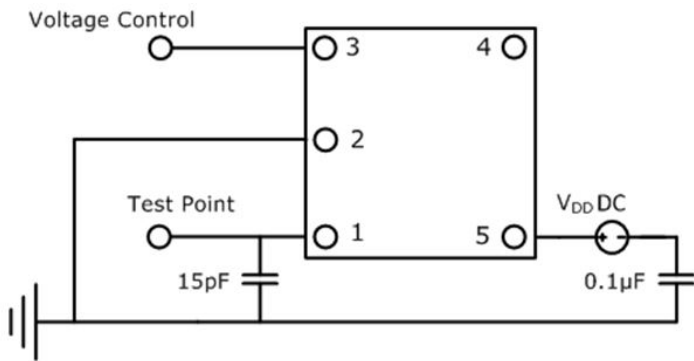
Electrical Parameters	Units	Minimum	Typical	Maximum	Remarks
Frequency Range	MHz	1		100	
Frequency Tolerance at +25°C	ppb	-100		+100	
Freq. Stability vs. Op Temp.	ppb	-50		+50	See part numbering guide for options.
Freq. Stability vs. Supply Voltage	ppb	-10		+10	V _{DD} ±5% Change
Freq. Stability vs. Load	ppb	-10		+10	±10% Change
Freq. Stability vs. Aging/Year	ppb	-500		+500	See part numbering guide for options.
Operating Temperature	°C	-20		+60	See part numbering guide for options.
Storage Temperature	°C	-45		+85	
Supply Voltage (V _{DD}) - 5.0V Option	V	4.750	5.0	5.250	
Supply Voltage (V _{DD}) - 9.0V Option	V	8.550	9.0	9.450	
Supply Voltage (V _{DD}) - 12.0V Option	V	11.40	12.0	12.60	
Power Consumption At Turn On	W			2.5	
Power Consumption At 25°C	W			1.0	
Control Voltage (V _c)	V	0.5		4.5	
Control Middle Voltage	V		2.5		
Pullability	ppm	±3.0	±5.0	±8.0	
Linearity	%			10	
V _c Input Impedance	KΩ	50			
Deviation Slope			Positive		
Output Logic (HCMOS)	pF			15	
Output Logic Level - High (V _{OH})	V	0.9*V _{DD}			
Output Logic Level - Low (V _{OL})	V			0.1*V _{DD}	
Rise Time (T _R) And Fall Time (T _F)	ns			5	
Symmetry (Duty Cycle)	%	45	50	55	
Start-Up Time	ms			3	
Warm-Up Time	ppb	-100		100	At 25°C After 5Mins.

Outline Drawing & Part Marking

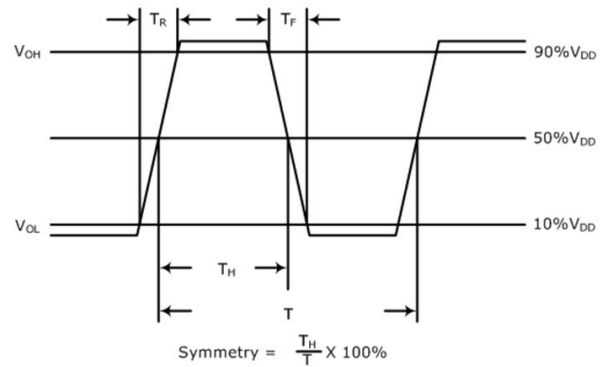
All dimensions are in millimeters (mm) unless otherwise noted. Drawings are not to scale.



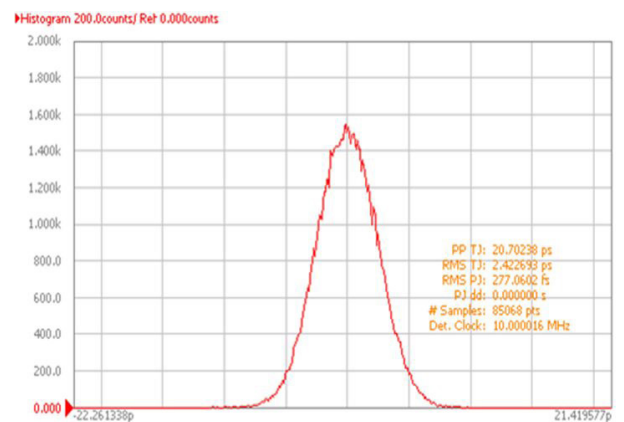
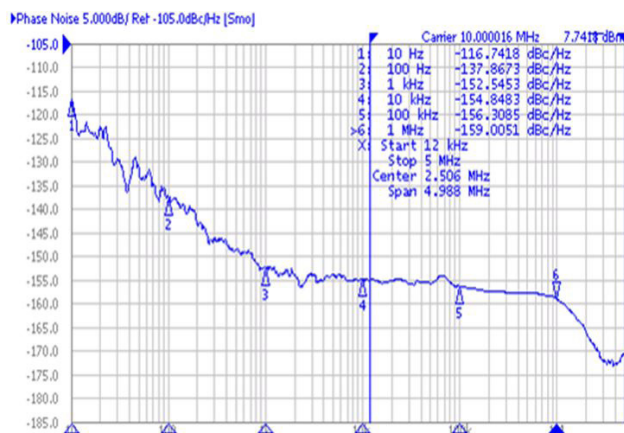
Test Circuit (HCMOS)



Waveform (HCMOS)



Typical Phase Noise And Jitter Performance (Measured By Agilent E5052A)



Frequency - 10.000MHz

Environmental Specifications		Mechanical Specifications	
Temperature Cycling	MIL-STD-883, Method 1010, Condition B	Mechanical Shock	MIL-STD-202, Method 213, Condition B
Lead Integrity	MIL-STD-883, Method 1014, Condition A	Vibration	MIL-STD-883, Method 2007, Condition A
Gross Leak Test	MIL-STD-883, Method 1014, Condition C	Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition A
Solderability	MIL-STD-883, Method 2003	Resistance to Solvents	MIL-STD-202, Method 215